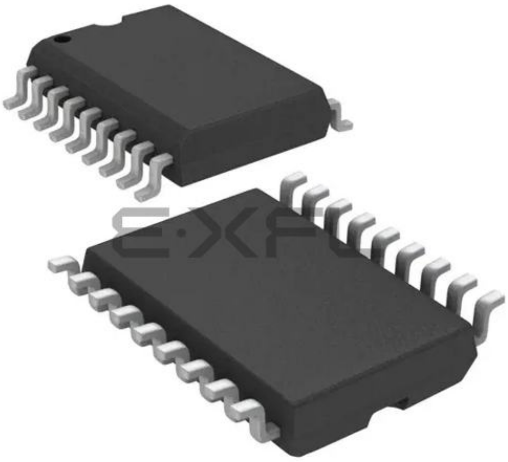
Microchip Technology - PIC16LC712-04I/SO Datasheet



Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc712-04i-so

Key Features PIC® Mid-Range Reference Manual (DS33023)	PIC16C712	PIC16C716
Operating Frequency	DC – 20 MHz	DC – 20 MHz
Resets (and Delays)	POR, BOR (PWRT, OST)	POR, BOR (PWRT, OST)
Program Memory (14-bit words)	1K	2K
Data Memory (bytes)	128	128
Interrupts	7	7
I/O Ports	Ports A,B	Ports A,B
Timers	3	3
Capture/Compare/PWM modules	1	1
8-bit Analog-to-Digital Module	4 input channels	4 input channels

PIC16C7XX FAMILY OF DEVICES

		PIC16C710	PIC16C71	PIC16C711	PIC16C712	PIC16C715	PIC16C716	PIC16C72A	PIC16C73B
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	1K	1K	2K	2K	2K	4K
	Data Memory (bytes)	36	36	68	128	128	128	128	192
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0 TMR1 TMR2	TMR0	TMR0 TMR1 TMR2	TMR0 TMR1 TMR2	TMR0 TMR1 TMR2
	Capture/Compare/ PWM Module(s)	—	—	—	1	—	1	1	2
	Serial Port(s) (SPI™/I^{2}C™, USART)	—	—	—	—	—	—	SPI/I^{2}C	SPI/I^{2}C, USART
	A/D Converter (8-bit) Channels	4	4	4	4	4	4	5	5
Features	Interrupt Sources	4	4	4	7	4	7	8	11
	I/O Pins	13	13	13	13	13	13	22	22
	Voltage Range (Volts)	2.5-6.0	3.0-6.0	2.5-6.0	2.5-5.5	2.5-5.5	2.5-5.5	2.5-5.5	2.5-5.5
	In-Circuit Serial Programming™	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	—	Yes	Yes	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC

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2.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and Peripheral Modules for controlling the desired operation of the device. These registers are implemented as static RAM. A list of these registers is give in Table 2-1.

The Special Function Registers can be classified into two sets; core (CPU) and peripheral. Those registers associated with the core functions are described in detail in this section. Those related to the operation of the peripheral features are described in detail in that peripheral feature section.

TABLE 2-1: SPECIAL FUNCTION REGISTER SUMMARY

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets (4)
Bank 0											
00h	INDF[1]	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
01h	TMR0	Timer0 Module's Register								xxxx xxxx	uuuu uuuu
02h	PCL[1]	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
03h	STATUS[1]	IRP[4]	RP1[4]	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	rr01 1xxx	rr0q quuu
04h	FSR[1]	Indirect Data Memory Address Pointer								xxxx xxxx	uuuu uuuu
05h	PORTA[5,6]	—	—	—[7]	PORTA Data Latch when written: PORTA pins when read					--xx xxxx	--xu uuuu
06h	PORTB[5,6]	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu
07h	DATACCP	—[7]	—[7]	—[7]	—[7]	—[7]	DCCP	—[7]	DT1CK	xxxx xxxx	xxxx xuxu
08h-09h	—	Unimplemented								–	–
0Ah	PCLATH[1,2]	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
0Bh	INTCON[1]	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	—	CCP1IF	TMR2IF	TMR1IF	-0-- 0000	-0-- 0000
0Dh	—	Unimplemented								–	–
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu
11h	TMR2	Timer2 Module's Register								0000 0000	0000 0000
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h-14h											
15h	CCPR1L	Capture/Compare/PWM Register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM Register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
18h-1Dh	—	Unimplemented								–	–
1Eh	ADRES	A/D Result Register								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON	0000 00-0	0000 00-0

Legend: x = unknown, u = unchanged, q = value depends on condition, — = unimplemented, read as '0', Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for PC<12:8> whose contents are transferred to the upper byte of the program counter.

3: Other (non Power-up) Resets include: external Reset through $\overline{\text{MCLR}}$ and the Watchdog Timer Reset.

4: The IRP and RP1 bits are reserved. Always maintain these bits clear.

5: On any device Reset, these pins are configured as inputs.

6: This is the value that will be in the port output latch.

7: Reserved bits; Do Not Use.

2.2.2.6 PCON Register

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external $\overline{\text{MCLR}}$ Reset or WDT Reset. These devices contain an additional bit to differentiate a Brown-out Reset condition from a Power-on Reset condition.

Note: If the BODEN Configuration bit is set, $\overline{\text{BOR}}$ is '1' on Power-on Reset. If the BODEN Configuration bit is clear, $\overline{\text{BOR}}$ is unknown on Power-on Reset.

The $\overline{\text{BOR}}$ Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (the BODEN Configuration bit is clear). $\overline{\text{BOR}}$ must then be set by the user and checked on subsequent resets to see if it is clear, indicating a brown-out has occurred.

FIGURE 2-9: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-q
—	—	—	—	—	—	$\overline{\text{POR}}$	$\overline{\text{BOR}}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{\text{POR}}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{\text{BOR}}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

2.5 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 2-1: INDIRECT ADDRESSING

- Register file 05 contains the value 10h
- Register file 06 contains the value 0Ah
- Load the value 05 into the FSR register
- A read of the INDF register will return the value of 10h
- Increment the value of the FSR register by one (FSR = 06)
- A read of the INDR register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = `0`) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although Status bits may be affected).

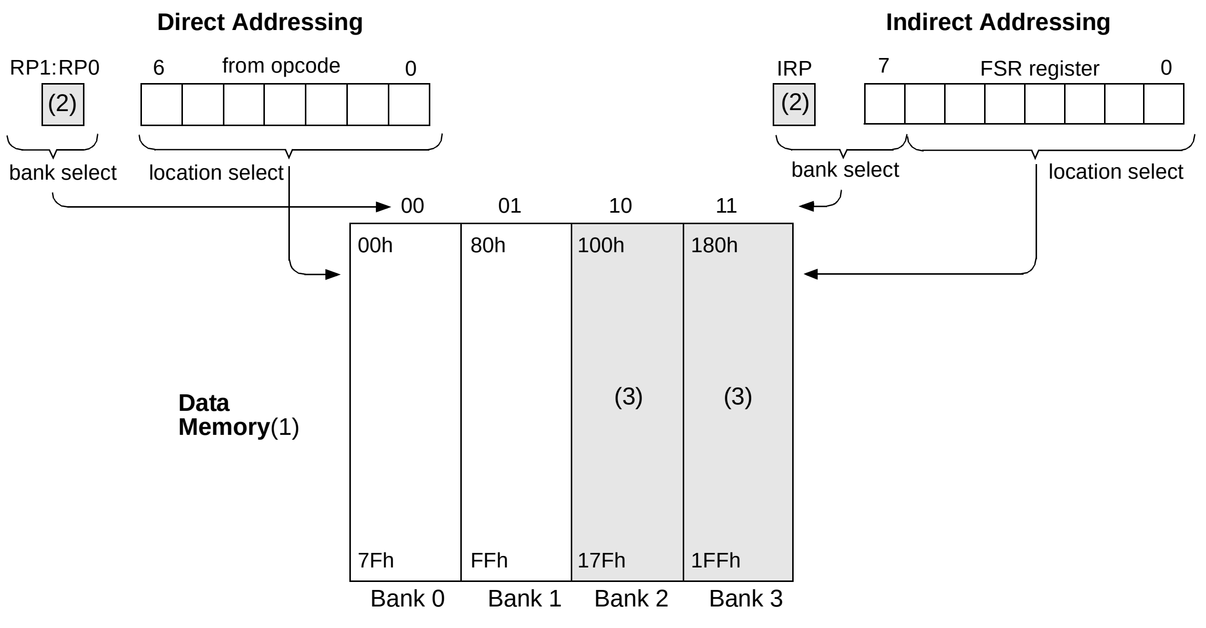
A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 2-2.

EXAMPLE 2-2: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

```
          MOVLW  0x20  ;initialize pointer
          MOVWF  FSR   ;  to RAM
NEXT      CLRF   INDF  ;clear INDF register
          INCF   FSR   ;inc pointer
          BTFSS  FSR,4 ;all done?
          GOTO   NEXT  ;NO, clear next
CONTINUE
          :            ;YES, continue
```

An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 2-10. However, IRP is not used in the PIC16C712/716.

FIGURE 2-10: DIRECT/INDIRECT ADDRESSING



Note 1: For register file map detail see Figure 2-3.
2: Maintain clear for upward compatibility with future products.
3: Not implemented.

PORTB pins RB3:RB1 are multiplexed with several peripheral functions (Table 3-3). PORTB pins RB3:RB0 have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTB pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modify-write instructions (`BSF, BCF, XORWF`) with TRISB as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

Four of PORTB's pins, RB7:RB4, have an interrupt-on-change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt-on-change comparison). The input pins, RB7:RB4, are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from Sleep. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

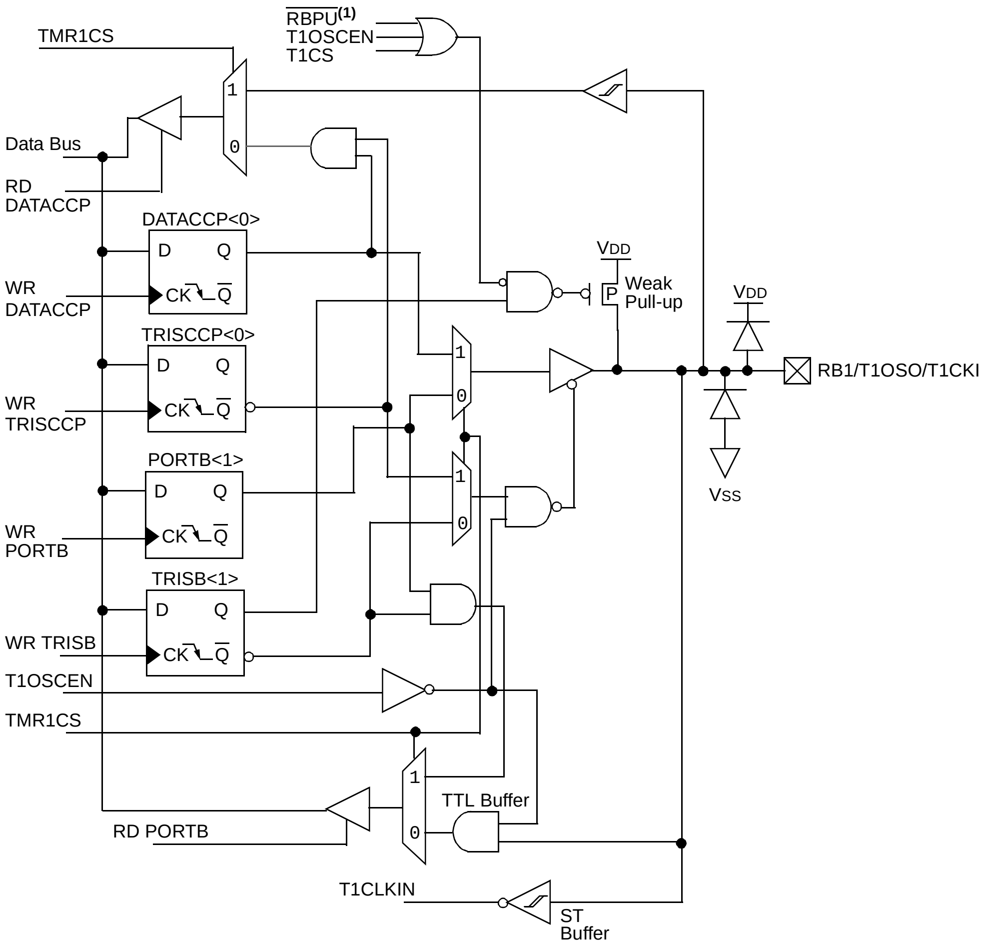
a) Any read or write of PORTB will end the mismatch condition.

b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

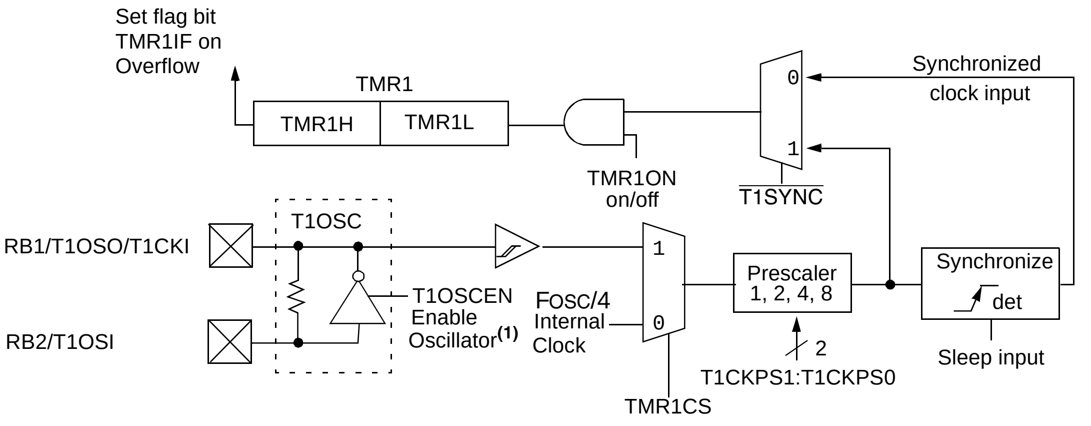
The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

FIGURE 3-4: BLOCK DIAGRAM OF RB1/T1OSO/T1CKI PIN



Note 1: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the RBPU bit (OPTION_REG<7>).

FIGURE 5-2: TIMER1 BLOCK DIAGRAM



Note 1: When the T1OSCEN bit is cleared, the inverter and feedback resistor are turned off. This eliminates power drain.

5.2 Timer1 Module and PORTB Operation

When Timer1 is configured as timer running from the main oscillator, PORTB<2:1> operate as normal I/O lines. When Timer1 is configured to function as a counter however, the clock source selection may affect the operation of PORTB<2:1>. Multiplexing details of the Timer1 clock selection on PORTB are shown in Figure 3-4 and Figure 3-5.

The clock source for Timer1 in the Counter mode can be from one of the following:

1. External circuit connected to the RB1/T1OSO/T1CKI pin
2. Firmware controlled DATACCP<0> bit, DT1CKI
3. Timer1 oscillator

Table 5-1 shows the details of Timer1 mode selections, control bit settings, TMR1 and PORTB operations.

TABLE 5-1: TMR1 MODULE AND PORTB OPERATION

TMR1 Module Mode	Clock Source	Control Bits	TMR1 Module Operation	PORTB<2:1> Operation
Off	N/A	T1CON = --xx 0x00	Off	PORTB<2:1> function as normal I/O
Timer	FOSC/4	T1CON = --xx 0x01	TMR1 module uses the main oscillator as clock source. TMR1ON can turn on or turn off Timer1.	PORTB<2:1> function as normal I/O
Counter	External circuit	T1CON = --xx 0x11 TR1SCCP = ---- -x-1	TMR1 module uses the external signal on the RB1/T1OSO/T1CKI pin as a clock source. TMR1ON can turn on or turn off Timer1. DT1CK can read the signal on the RB1/T1OSO/T1CKI pin.	PORTB<2> functions as normal I/O. PORTB<1> always reads '0' when configured as input. If PORTB<1> is configured as output, reading PORTB<1> will read the data latch. Writing to PORTB<1> will always store the result in the data latch, but not to the RB1/T1OSO/T1CKI pin. If the TMR1CS bit is cleared (TMR1 reverts to the timer mode), then pin PORTB<1> will be driven with the value in the data latch.
	Firmware	T1CON = --xx 0x11 TR1SCCP = ---- -x-0	DATACCP<0> bit drives RB1/T1OSO/T1CKI and produces the TMR1 clock source. TMR1ON can turn on or turn off Timer1. The DATACCP<0> bit, DT1CK, can read and write to the RB1/T1OSO/T1CKI pin.	
	Timer1 oscillator	T1CON = --xx 1x11	RB1/T1OSO/T1CKI and RB2/T1OSI are configured as a 2 pin crystal oscillator. RB1/T1OSI/T1CKI is the clock input for TMR1. TMR1ON can turn on or turn off Timer1. DATACCP<1> bit, DT1CK, always reads '0' as input and can not write to the RB1/T1OSO/T1CK1 pin.	PORTB<2:1> always read '0' when configured as inputs. If PORTB<2:1> are configured as outputs, reading PORTB<2:1> will read the data latches. Writing to PORTB<2:1> will always store the result in the data latches, but not to the RB2/T1OSI and RB1/T1OSO/T1CKI pins. If the TMR1CS and T1OSCEN bits are cleared (TMR1 reverts to the timer mode and TMR1 oscillator is disabled), then pin PORTB<2:1> will be driven with the value in the data latches.

8.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) Converter module has four inputs.

The A/D allows conversion of an analog input signal to a corresponding 8-bit digital number (refer to Application Note AN546 for use of A/D Converter). The output of the sample and hold is the input into the converter, which generates the result via successive approximation. The analog reference voltage is software selectable to either the device's positive supply voltage (VDD) or the voltage level on the RA3/AN3/VREF pin.

The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

Additional information on the A/D module is available in the PIC® Mid-Range Reference Manual, (DS33023).

The A/D module has three registers. These registers are:

- A/D Result Register (ADRES)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off, and any conversion is aborted.

The ADCON0 register, shown in Figure 8-1, controls the operation of the A/D module. The ADCON1 register, shown in Figure 8-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be a voltage reference) or as digital I/O.

FIGURE 8-1: ADCON0 REGISTER (ADDRESS 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	$\overline{\text{ADON}}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7-6: **ADCS1:ADCS0:** A/D Conversion Clock Select bits
00 = FOSC/2
01 = FOSC/8
10 = FOSC/32
11 = FRC (clock derived from the internal ADC RC oscillator)

bit 5-3: **CHS2:CHS0**: Analog Channel Select bits
000 = channel 0, (RA0/AN0)
001 = channel 1, (RA1/AN1)
010 = channel 2, (RA2/AN2)
011 = channel 3, (RA3/AN3)
1xx = reserved, do not use

bit 2: **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit

If ADON = 1
1 = A/D conversion in progress (setting this bit starts the A/D conversion)
0 = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conversion is complete)

bit 1: **Unimplemented**: Read as '0'

bit 0: **ADON**: A/D On bit
1 = A/D converter module is operating
0 = A/D converter module is shutoff and consumes no operating current

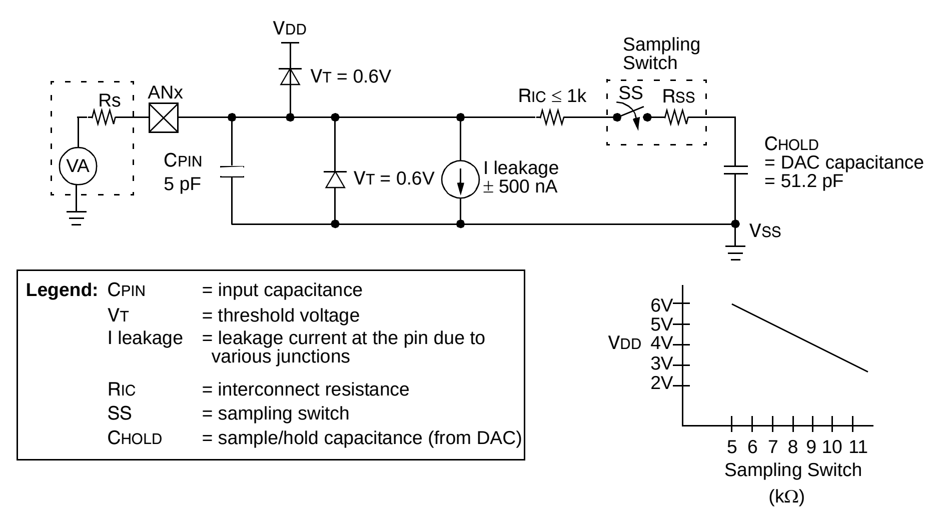
8.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the Charge Holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 8-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 10 kΩ**. After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, TACQ, see the PIC® Mid-Range Reference Manual, (DS33023). This equation calculates the acquisition time to within 1/2 LSb error (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

FIGURE 8-4: ANALOG INPUT MODEL



8.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 9.5TAD per 8-bit conversion. The source of the A/D conversion clock is software selectable. The four possible options for TAD are:

- 2TOSC
- 8TOSC
- 32TOSC
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 μs.

Table 8-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

8.3 Configuring Analog Port Pins

The ADCON1 and TRISA registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

Note 1: When reading the port register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.

2: Analog levels on any pin that is defined as a digital input (including the AN3:AN0 pins), may cause the input buffer to consume current that is out of the devices specification.

TABLE 8-1: TAD VS. DEVICE OPERATING FREQUENCIES

AD Clock Source (TAD)		**Device Frequency**			
Operation	**ADCS1:ADCS0**	**20 MHz**	**5 MHz**	**1.25 MHz**	**333.33 kHz**
2TOSC	`00`	100 ns(2)	400 ns(2)	1.6 μs	6 μs
8TOSC	`01`	400 ns(2)	1.6 μs	6.4 μs	24 μs(3)
32TOSC	`10`	1.6 μs	6.4 μs	25.6 μs(3)	96 μs(3)
RC(5)	`11`	2-6 μs(1,4)	2-6 μs(1,4)	2-6 μs(1,4)	2-6 μs(1)

Legend: Shaded cells are outside of recommended range.

Note 1: The RC source has a typical TAD time of 4 μs.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When device frequency is greater than 1 MHz, the RC A/D conversion clock source is recommended for Sleep operation only.

5: For extended voltage devices (LC), please refer to Electrical Specifications section.

FIGURE 9-11: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO VDD)

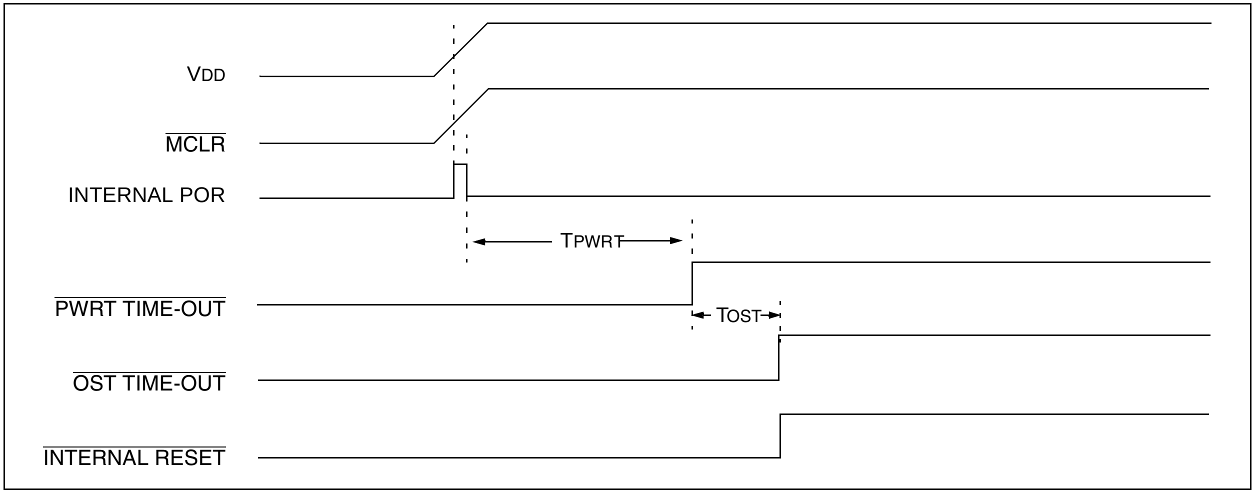


FIGURE 9-12: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO VDD): CASE 1

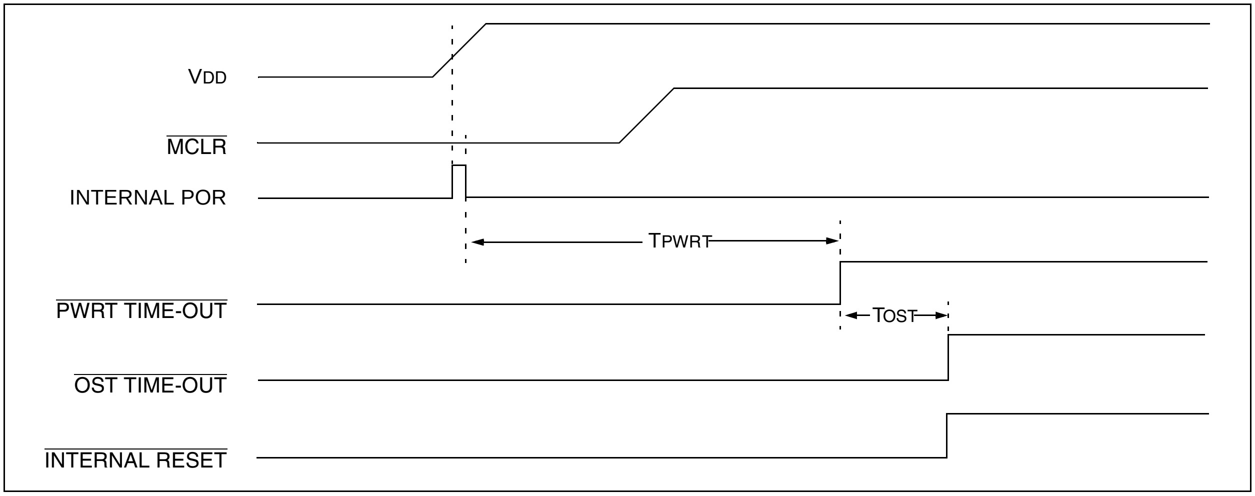
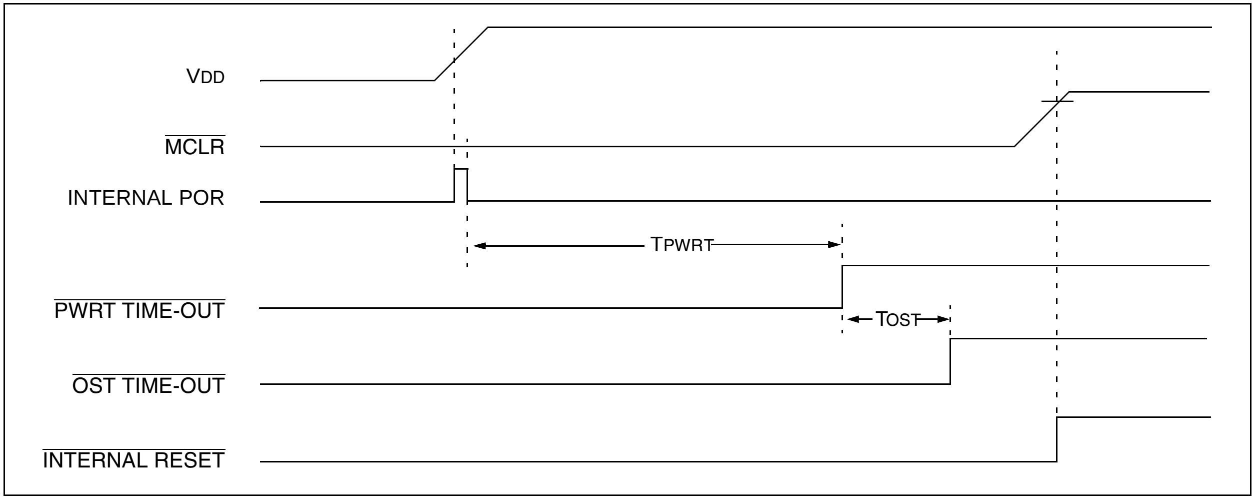


FIGURE 9-13: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO VDD): CASE 2



9.12 Watchdog Timer (WDT)

The Watchdog Timer is as a free running, on-chip, RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run, even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device have been stopped, for example, by execution of a `SLEEP` instruction.

During normal operation, a WDT Time-out generates a device Reset (Watchdog Timer Reset). If the device is in Sleep mode, a WDT Time-out causes the device to wake-up and continue with normal operation (Watchdog Timer Wake-up). The $\overline{\text{TO}}$ bit in the STATUS register will be cleared upon a Watchdog Timer Time-out.

The WDT can be permanently disabled by clearing Configuration bit WDTE (**Section 9.1 "Configuration Bits"**).

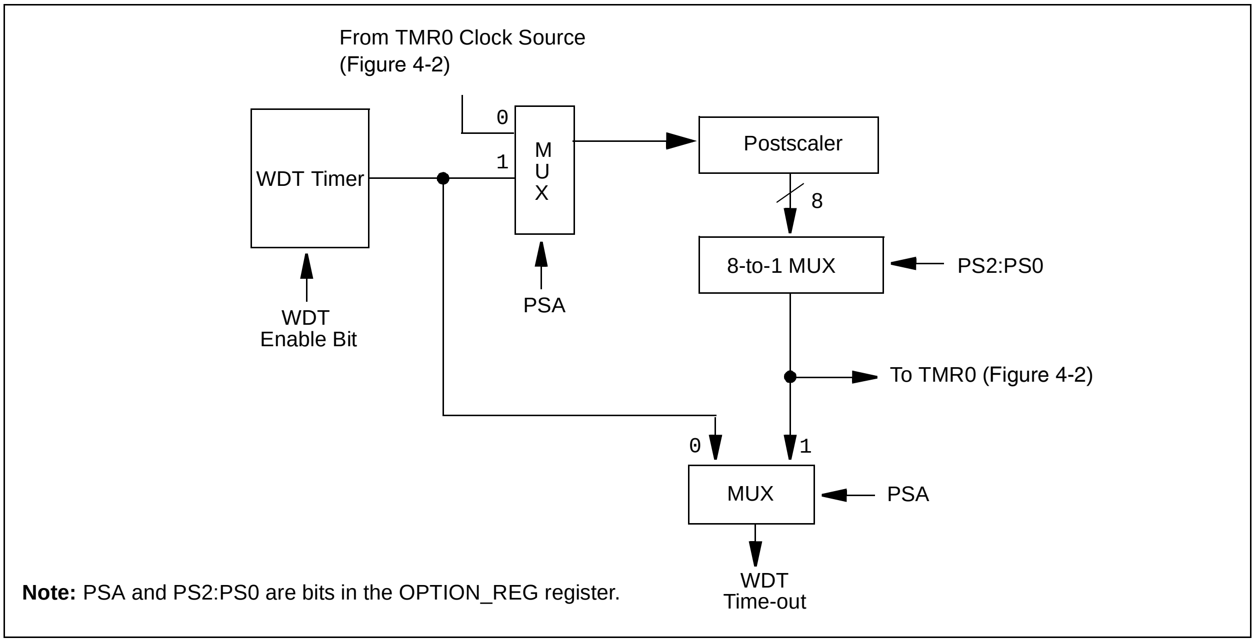
WDT time-out period values may be found in the Electrical Specifications section under TWDT (parameter #31). Values for the WDT prescaler (actually a postscaler, but shared with the Timer0 prescaler) may be assigned using the OPTION_REG register.

Note: The `CLRWDT` and `SLEEP` instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device Reset condition.

.

Note: When a `CLRWDT` instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared, but the prescaler assignment is not changed.

FIGURE 9-15: WATCHDOG TIMER BLOCK DIAGRAM



Note: PSA and PS2:PS0 are bits in the OPTION_REG register.

FIGURE 9-16: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bits 13:8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits	**(1)**	—	BODEN(1)	$\overline{\text{CP1}}$	$\overline{\text{CP0}}$	$\overline{\text{PWRTE}}$(1)	WDTE	FOSC1	FOSC0
81h	OPTION_REG	N/A	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0

Legend: Shaded cells are not used by the Watchdog Timer.
Note 1: See Figure 9-1 for operation of these bits.

9.16 In-Circuit Serial Programming™

PIC16CXXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

For complete details on serial programming, please refer to the In-Circuit Serial Programming™ (ICSP™) Guide, (DS30277).

12.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (†)

Ambient temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{\text{MCLR}}$, and RA4)	-0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS}	-0.3V to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to V_{SS} **(Note 2)**	0V to +13.25V
Voltage on RA4 with respect to Vss	0V to +8.5V
Total power dissipation **(Note 1)** (PDIP and SOIC)	1.0W
Total power dissipation **(Note 1)** (SSOP)	0.65W
Maximum current out of V_{SS} pin	300 mA
Maximum current into V_{DD} pin	250 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA and PORTB (combined)	200 mA
Maximum current sourced by PORTA and PORTB (combined)	200 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{\text{MCLR}}$/V_{PP} pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$/V_{PP} pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

12.1 DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D001	VDD	Supply Voltage	4.0	—	5.5	V	XT, RC and LP osc mode
D001A			4.5	—	5.5	V	HS osc mode
			VBOR*	—	5.5	V	BOR enabled(7)
D002*	VDR	**RAM Data Retention Voltage(1)**	—	1.5	—	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See section on Power-on Reset for details
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	PWRT enabled ($\overline{\text{PWRTE}}$ bit clear)
D004A*			TBD	—	—		PWRT disabled ($\overline{\text{PWRTE}}$ bit set)
							See section on Power-on Reset for details
D005	VBOR	**Brown-out Reset** voltage trip point	3.65	—	4.35	V	BODEN bit set
D010	IDD	**Supply Current(2,5)**	—	0.8	2.5	mA	FOSC = 4 MHz, VDD = 4.0V
D013			—	4.0	8.0	mA	FOSC = 20 MHz, VDD = 4.0V
D020	IPD	**Power-down Current(3,5)**	—	10.5	42	µA	VDD = 4.0V, WDT enabled,-40°C to +85°C
			—	1.5	16	µA	VDD = 4.0V, WDT disabled, 0°C to +70°C
D021			—	1.5	19	µA	VDD = 4.0V, WDT disabled,-40°C to +85°C
D021B			—	2.5	19	µA	VDD = 4.0V, WDT disabled,-40°C to +125°C
		Module Differential Current(6)					
D022*	ΔIWDT	Watchdog Timer	—	6.0	20	µA	WDTE bit set, VDD = 4.0V
D022A*	ΔIBOR	Brown-out Reset	—	TBD	200	µA	BODEN bit set, VDD = 5.0V
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	KHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and VSS.

4: For RC Osc mode, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will operate correctly to this trip point.

12.3 DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712716-20 (Commercial, Industrial, Extended) PIC16LC712/716-04 (Commercial, Industrial)

DC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C $\leq T_A \leq$ +70°C for commercial -40°C $\leq T_A \leq$ +85°C for industrial -40°C $\leq T_A \leq$ +125°C for extended Operating voltage V_{DD} range as described in DC spec **Section 12.1 “DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)”** and **Section 12.2 “DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)”**

Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
		Input Low Voltage					
	V_{IL}	I/O ports					
D030		with TTL buffer	Vss	—	0.8V	V	4.5V $\leq V_{DD} \leq$ 5.5V
D030A			Vss	—	$0.15V_{DD}$	V	otherwise
D031		with Schmitt Trigger buffer	Vss	—	$0.2V_{DD}$	V	
D032		$\overline{MCLR}$, OSC1 (in RC mode)	Vss	—	$0.2V_{DD}$	V	
D033		OSC1 (in XT, HS and LP modes)	Vss	—	$0.3V_{DD}$	V	**(Note 1)**
		Input High Voltage					
	V_{IH}	I/O ports		—			
D040		with TTL buffer	2.0	—	V_{DD}	V	4.5V $\leq V_{DD} \leq$ 5.5V
D040A			$0.25V_{DD}$ + 0.8V	—	V_{DD}	V	otherwise
D041		with Schmitt Trigger buffer	$0.8V_{DD}$	—	V_{DD}	V	For entire V_{DD} range
D042		$\overline{MCLR}$	$0.8V_{DD}$	—	V_{DD}	V	
D042A		OSC1 (XT, HS and LP modes)	$0.7V_{DD}$	—	V_{DD}	V	**(Note 1)**
D043		OSC1 (in RC mode)	$0.9V_{DD}$	—	V_{DD}	V	
		Input Leakage Current (Notes 2, 3)					
D060	I_{IL}	I/O ports	—	—	±1	μA	$V_{SS} \leq V_{PIN} \leq V_{DD}$, Pin at high-impedance
D061		$\overline{MCLR}$, RA4/T0CKI	—	—	±5	μA	$V_{SS} \leq V_{PIN} \leq V_{DD}$
D063		OSC1	—	—	±5	μA	$V_{SS} \leq V_{PIN} \leq V_{DD}$, XT, HS and LP osc modes
D070	I_{PURB}	**PORTB weak pull-up current**	50	250	400	μA	V_{DD} = 5V, $V_{PIN} = V_{SS}$

* These parameters are characterized but not tested.

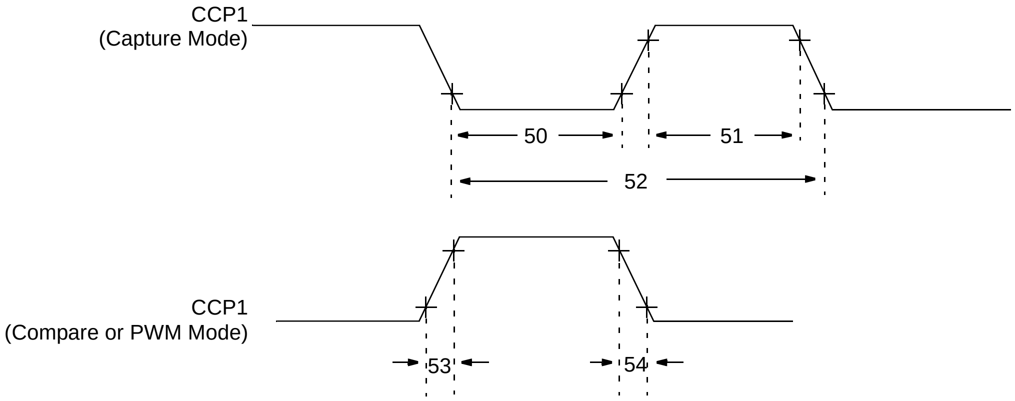
† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC Oscillator mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC MCU be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}/V_{PP}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

FIGURE 12-9: CAPTURE/COMPARE/PWM TIMINGS



Note: Refer to Figure 12-3 for load conditions.

TABLE 12-6: CAPTURE/COMPARE/PWM REQUIREMENTS

Param No.	Sym.	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard	10	—	—	ns	
				Extended (LC)	20	—	—	ns	
51*	TccH	CCP1 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard	10	—	—	ns	
				Extended (LC)	20	—	—	ns	
52*	TccP	CCP1 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4, or 16)
53*	TccR	CCP1 output rise time		Standard	—	10	25	ns	
				Extended (LC)	—	25	45	ns	
54*	TccF	CCP1 output fall time		Standard	—	10	25	ns	
				Extended (LC)	—	25	45	ns	

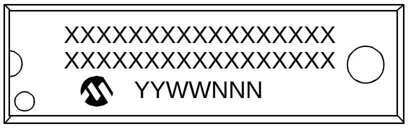
* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

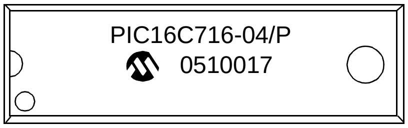
13.0 PACKAGING INFORMATION

13.1 Package Marking Information

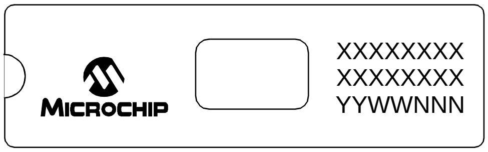
18-Lead PDIP



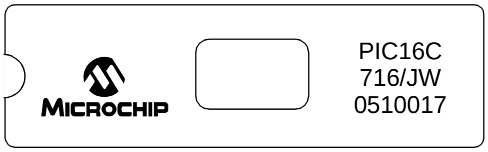
Example



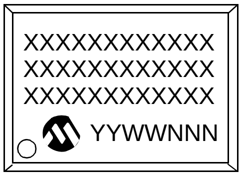
18-Lead CERDIP Windowed



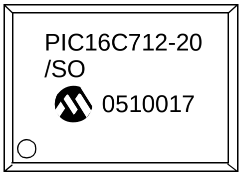
Example



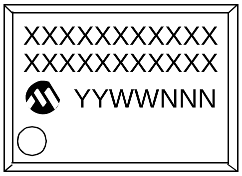
18-Lead SOIC (.300”)



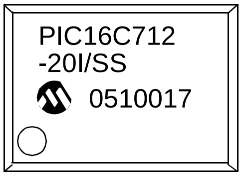
Example



20-Lead SSOP



Example

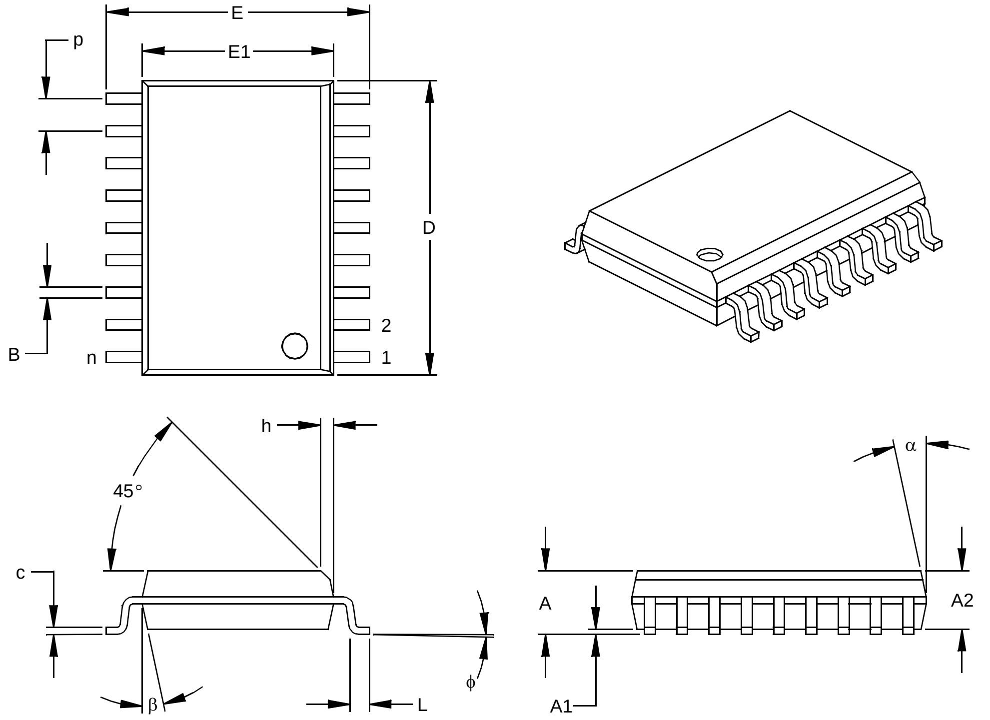


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*****	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051